Unit: mm

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (Ultra-High-Speed U-MOSIII)

# **TPC6109-H**

#### High-Efficiency DC/DC Converter Applications

· Small footprint due to small and thin package

- Low drain-source ON-resistance: RDS (ON) = 44 m $\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 8.0 \text{ S (typ.)}$
- Low leakage current:  $I_{DSS} = -10 \mu A \text{ (max) (V}_{DS} = -30 \text{ V)}$
- Enhancement mode:  $V_{th}$  = -0.8 to -2.0 V ( $V_{DS}$  = -10 V,  $I_{D}$  = -1 mA)

#### Absolute Maximum Ratings (Ta = 25°C)

Characteristics			Symbol	Rating	Unit	
Drain-source volta	ge		$V_{DSS}$	-30	V	
Drain-gate voltage	Drain-gate voltage (R <sub>GS</sub> = 20 k $\Omega$ )			-30	V	
Gate-source voltage			$V_{GSS}$	±20	V	
Drain current	DC	(Note 1)	I <sub>D</sub>	-5	Α	
	Pulse	(Note 1)	I <sub>DP</sub>	-20		
Drain power dissip	Drain power dissipation (t = 5 s) (Note 2a)			2.2	W	
Drain power dissip	oation (t = 5 s)	$P_{D}$	0.7	VV		
Single-pulse avalanche energy (Note 3)			E <sub>AS</sub>	16.3	mJ	
Avalanche current			I <sub>AR</sub>	-5	Α	
Repetitive avalanche energy Single-device value at dual operation (Note 4)			E <sub>AR</sub>	0.055	mJ	
Channel temperature			T <sub>ch</sub>	150	°C	
Storage temperature range			T <sub>stg</sub>	-55 to150	°C	

1. Drain 5. Drain 3. Gate 6. Drain 5. Drain 3. Gate —

JEDEC —

JEITA —

TOSHIBA 2-3T1A

Weight: 0.011 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

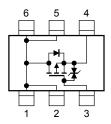
#### Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient $(t = 5 \text{ s})$ (Note 2a)	R <sub>th (ch-a)</sub>	56.8	°C/W
Thermal resistance, channel to ambient $(t = 5 \text{ s})$ (Note 2b)	R <sub>th (ch-a)</sub>	178.5	°C/W

Note: For Notes 1 to 5, see page 3.

Caution: This transistor is an electrostatic-sensitive device. Handle with care.

#### **Circuit Configuration**





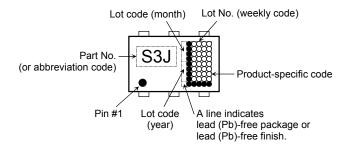
# **Electrical Characteristics (Ta = 25°C)**

Ch	aracteristic	Symbol	Test Condition	Test Condition Min Typ. Max		Unit	
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	— <u>±</u> 10		μА	
Drain cut-off curr	ent	I <sub>DSS</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	_		-10	μА
Danis and the state of the state of		V (BR) DSS	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-30	_	_	V
Diain-source bre	urce breakdown voltage		$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	-15	_	_	
Gate threshold vo	oltage	V <sub>th</sub>	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$	-0.8	_	-2.0	V
Drain-source ON	rocistanco	R <sub>DS</sub> (ON)	$V_{GS} = -4.5 \text{ V}, I_D = -2.5 \text{ A}$	_	64	83	mO
Dialii-source ON	resistance	R <sub>DS</sub> (ON)	$V_{GS} = -10 \text{ V}, I_D = -2.5 \text{ A}$	—     44     59		mΩ	
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = -10 \text{ V}, I_D = -2.5 \text{ A}$	4.0 8.0 —		_	S
Input capacitance	9	C <sub>iss</sub>		_	490	_	pF
Reverse transfer	capacitance	C <sub>rss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	105	_	
Output capacitance		Coss		_	150	_	
Switching time	Rise time	t <sub>r</sub>	V <sub>GS</sub> 0 V   I <sub>D</sub> = -2.5 A   V <sub>GS</sub> 0 V <sub>OUT</sub>   C <sub>G</sub> 0 V <sub>OUT</sub>   C	_	5.1	_	- ns
	Turn-on time	t <sub>on</sub>		_	10.7	_	
	Fall time	t <sub>f</sub>		_	8.0	_	
	Turn-off time	t <sub>off</sub>	V <sub>DD</sub> ≃ −15 V Duty ≦ 1%, t <sub>W</sub> = 10 μs	_	33.5	_	
Total gate charge (gate-source plus gate-drain)		0	$\begin{split} V_{DD} &\simeq -24 \text{ V, V}_{GS} = -10 \text{ V,} \\ I_D &= -5 \text{ A} \end{split}$	_	12.3	_	nC
		Qg	$V_{DD} \simeq -24 \text{ V}, V_{GS} = -5 \text{ V},$ $I_D = -5 \text{ A}$	_	7.2	_	
Gate-source charge1		Q <sub>gs1</sub>	$V_{DD} \simeq -24 \text{ V}, V_{GS} = -10 \text{ V},$ $I_{D} = -5 \text{ A}$	_	1.7		
Gate-drain ("Miller") charge		Q <sub>gd</sub>		_	3.6	_	
Gate switch char	ge	Qsw		_	4.8	_	

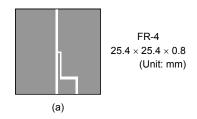
## Source-Drain Ratings and Characteristics (Ta = 25°C)

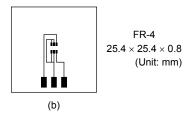
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	-20	Α
Forward voltage (diode)		V <sub>DSF</sub>	$I_{DR} = -5 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

## Marking (Note 5)



- Note 1: Ensure that the channel temperature does not exceed 150°C.
- Note 2: (a) Device mounted on a glass-epoxy board (a) (t = 5 s)
  - (b) Device mounted on a glass-epoxy board (b) (t = 5 s)

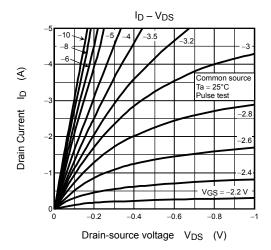


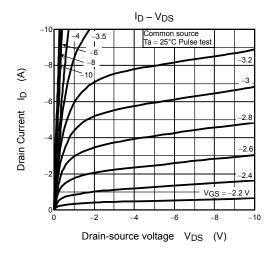


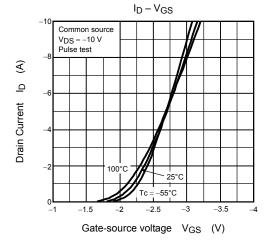
Note 3:  $V_{DD} = -24~V, T_{ch} = 25^{\circ}C$  (initial),  $L = 500~\mu H,~R_G = 25~\Omega,~I_{AR} = -5~A$ 

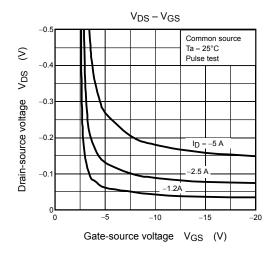
Note 4: Repetitive rating: pulse width limited by max channel temperature

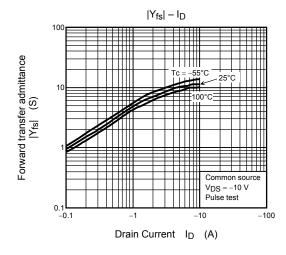
Note 5: ● to the lower left of the Part No. marking indicates Pin 1.

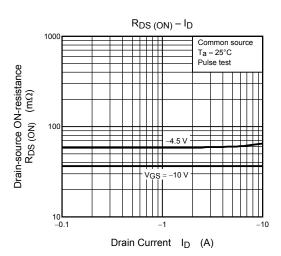




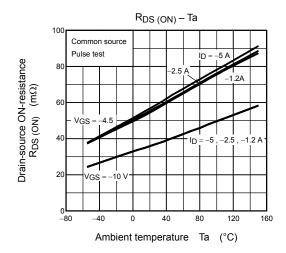


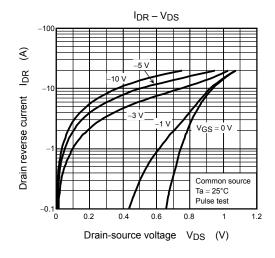


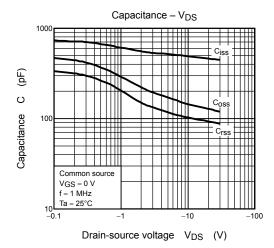


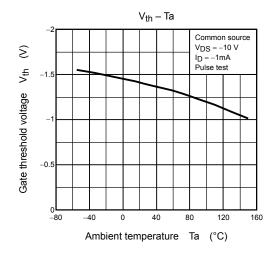


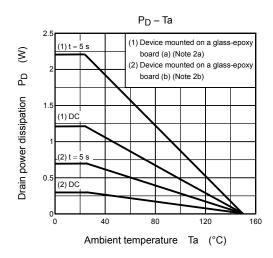
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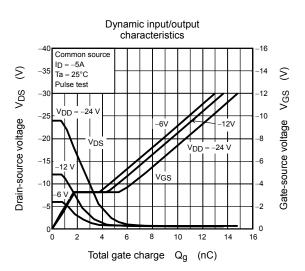




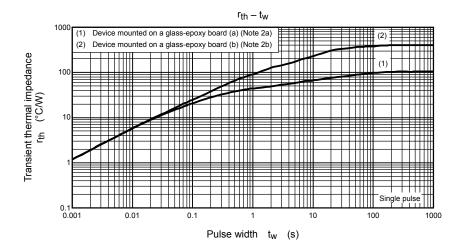


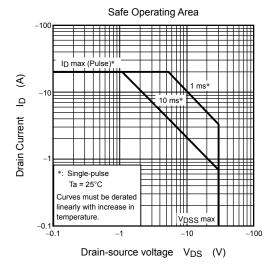






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